

Title of Change:	ON Semiconductor SBN Malaysia Assembly site qualification of NCP81078/80 for capacity expansion.					
Proposed first ship date:	6 November 2019					
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>clarence.wong@onsemi.com</u> >					
Samples:	Contact your local ON Semiconductor Sales Office Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.					
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or MohdAzizi.Azman@onsemi.com>.					
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < <u>PCN.Support@onsemi.com></u>					
Change Part Identification:	Affected products will be identified by the site marking date code.					
Change Category:	Wafer Fab Change Assembly Change Test Change Other Site Addition Site Addition					
Change Sub-Category(s):						
Manufacturing Site Additi	Manufacturing Site Addition Material Change Datasheet/Product Doc change					
Manufacturing Site Transfe						
Manufacturing Process Change						
Sites Affected:	ON Semiconductor Sites: External Foundry/Subcon Sites: None					
Description and Purpose:						
Assembly qualification of NCP81078/80 in ON Semiconductor SBN Malaysia. The qualification includes the use of qualified assembly material used in products running in similar packages in SBN assembly site.						
	UTL assembly BOM	SBN Assembly BOM				
LeadFrame	FR1056 (LF DFN8 2x2 .5P (Matte Sn))	N03949G003 (SELECTIVE Ag PLATED LEADFRAME DFN2020-8L WITH SURFACE TREATMENT)				
Die Attach	PZ0035 (ABLETHERM 8600 CONDUCTIVE)	B04879C040 (DA AB 8008 CON 10CC)				
Bond Wire	WZ0041 (BW AuPd-COATED Cu .8 mils)	N40363E011 (0.8 mil Tanaka CLK-1BK PCC Wire)				
Mold Compound	CZ0289 (MC G700LTD)	N99978F002 (Sumitomo EME-G770HM Type D)				
Assembly Site	UTL	SBN				
Mold Compound	CZ0289 (MC G700LTD)	N99978F002 (Sumitomo EME-G770HM Type D)				



		From		То	
		UTL assembly site marking XX = Specified Device Code M = Date Code • = Pb-Free Device (Note: Microdot may be in either location)	XX = Spec M = Date = eps-f (Note: Mi SBN assem XX = Spec M = Date = eps-f M = Date = eps-f M = Date	XX The The Specified Device Code M = Date Code The Phree Device (Note: Microdot may be in either location) SBN assembly site marking (new site)	
	ata Summary: AME : <u>NCP81078MNT</u> <u>S54345,S54861</u> <u>DFN8 2X2X0.91</u>				
Test	Specifica	ation Condition	n	Interval	Results
HTSL	JESD22-			1008 hrs	0/252
тс	JESD22-			1000 cyc	0/252
HAST	JESD22-			96 hrs	0/252
uHAST	JESD22-			96 hrs	0/252
РС	J-STD-020 JE				0/756
· -	JESD22-				0/90
RSH					



List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.

Part Number	Qualification Vehicle	
NCP81078MNTBG	NCP81078MNTBG	
NCP81080MNTBG		